

**Notic of References Cited**

Application/Control No.

09/903,792

Applicant(s)/Patent Under

Reexamination

NAKATA ET AL.

Examiner

Kripa Sagar

Art Unit

1756

Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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	B	US-2002/0076657	06-2002	Towata, Shuichi	430/322
	C	US-2002/0094382	07-2002	Imai et al.	427/282
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	M	US-			

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Thick Film Processes"; in Hybrid Microcircuit Technology Handbook, (Noyes, 1998), ch.4; pp. 104-171.
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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